

Appl. No. 10/675,049 Amdt. dated 5/15/06
Reply to Office action of February 16, 2006

SPECIFICATION AMENDMENTS

) A new Abstract as amended appears on a separate sheet.

Please amend the Abstract as follows:

Abstract of the Disclosure:

~~The invention relates to a~~ A method and ~~to~~ a furnace are
provided for the vapor phase deposition of components onto
semiconductor substrates. The main flow direction of the
process gases can be varied or reversed by the furnace in the
course of the method. This prevents temperature and
concentration inhomogeneities of the process gas within the
furnace, and permits the components to be uniformly deposited
onto the semiconductor substrates.